BS EN IEC 62878-1:2019

BSI Standards Publication

Device embedding assembly technology

Part 1: Generic specification for device embedded substrates

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National foreword

This British Standard is the UK implementation of EN IEC 62878-1:2019. It is identical to IEC 62878-1:2019.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its secretary.

This publication does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

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Published by BSI Standards Limited 2019

ISBN 978 0 580 97304 8

ICS 31.180; 31.190

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This British Standard was published under the authority of the Standards Policy and Strategy Committee on 31 December 2019.

Amendments/corrigenda issued since publication

Date	Text affected

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EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN IEC 62878-1

December 2019

ICS 31.180; 31.190

English Version

Device embedding assembly technology - Part 1: Generic specification for device embedded substrates (IEC 62878-1:2019)

Techniques d'assemblage avec appareil(s) integre(s) - Partie 1: Spécification générique pour substrats avec appareil(s) intégré(s) (IEC 62878-1:2019)

Montageverfahren für eingebettete Bauteile - Teil 1: Fachgrundspezifikation für Trägermaterial mit eingebetteten Bauteilen (IEC 62878-1:2019)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

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European foreword

The text of document 91/1597/FDIS, future edition 1 of IEC 62878-1, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62878-1:2019.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2020-08-18
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2022-11-18

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 62878-1:2019 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-1:2013	NOTE	Harmonized as EN 60068-1:2014 (not modified)
IEC 60068-2-45	NOTE	Harmonized as EN 60068-2-45
IEC 60068-2-58	NOTE	Harmonized as EN 60068-2-58
IEC/TR 61340-5-2	NOTE	Harmonized as CLC/TR 61340-5-2
IEC 62421	NOTE	Harmonized as EN 62421

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Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

Publication	Year	Title	EN/HD	Year
IEC 60068-2-1	-	Environmental testing - Part 2-1: Tests - Test A: Cold	EN 60068-2-1	-
IEC 60068-2-2	-	Environmental testing - Part 2-2: Tests - Test B: Dry heat	EN 60068-2-2	-
IEC 60068-2-6	-	Environmental testing - Part 2-6: Tests - Test Fc: Vibration (sinusoidal)	EN 60068-2-6	-
IEC 60068-2-14	-	Environmental testing - Part 2-14: Tests - Test N: Change of temperature	EN 60068-2-14	-
IEC 60068-2-21	-	Environmental testing - Part 2-21: Tests - Test U: Robustness of terminations and integral mounting devices	EN 60068-2-21	-
IEC 60068-2-27	-	Environmental testing - Part 2-27: Tests - Test Ea and guidance: Shock	EN 60068-2-27	-
IEC 60068-2-69	-	Environmental testing – Part 2-69: Tests – Test Te/Tc: Solderability testing of electronic components and printed boards by the wetting balance (force measurement) method	EN 60068-2-69	-
IEC 60068-2-78	-	Environmental testing - Part 2-78: Tests - Test Cab: Damp heat, steady state	EN 60068-2-78	-
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-
IEC 61340-5-1	-	Electrostatics - Part 5-1: Protection of electronic devices from electrostatic phenomena - General requirements	EN 61340-5-1	-

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Publication	Year	Title	EN/HD	Year
IEC 61340-5-3	-	Electrostatics - Part 5-3: Protection of electronic devices from electrostatic phenomena - Properties and requirements classification for packaging intended for electrostatic discharge sensitive devices	EN 61340-5-3	-
IEC 61760-4	-	Surface mounting technology - Part 4: Classification, packaging, labelling and handling of moisture sensitive devices	EN 61760-4	-
IEC 62137-1-4	-	Surface mounting technology - Environmental and endurance test methods for surface mount solder joint - Part 1-4: Cyclic bending test	EN 62137-1-4	-
IEC 62878-1-1	-	Device embedded substrate - Part 1-1: Generic specification - Test methods	EN 62878-1-1	-
IEC/TR 62878-2-2	-	Device embedded substrate - Part 2-2: Guidelines - Electrical testing	-	-
IEC/TS 62878-2-1	-	Device embedded substrate - Part 2-1: Guidelines - General description of technology	-	-
IEC/TS 62878-2-3	-	Device embedded substrate - Part 2-3: Guidelines - Design guide	-	-
IEC/TS 62878-2-4	-	Device embedded substrate - Part 2-4: Guidelines - Test element groups (TEG)	-	-
J-STD 033	-	Handling, Packing, Shipping, and Use of Moisture/Reflow and/or Process Sensitive Components	-	-

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Full document details: BS EN IEC 62878-1:2019

CONTENTS

FOREWORD 4
INTRODUCTION 6
1 Scope 7
2 Normative references 7
3 Terms and definitions 8
4 Value chain 8
4.1 System description 8
4.1.1 Generic design variants 8
4.1.2 Generic value chain 8
4.2 Elements of the value chain 9
4.2.1 General 9
4.2.2 System manufacturer 9
4.2.3 Components manufacturer 9
4.2.4 Material manufacturer 10
4.2.5 Submodule manufacturer 10
4.2.6 Board manufacturer 10
4.2.7 Assembly manufacturer 10
4.3 Traceability 10
5 Safety aspects of base material and components 10
6 Design and structure of device embedded substrate 11
6.1 Basic rules for layer description 11
6.2 Design for embedding and testability 11
6.3 Safety aspects of design 11
7 Embedding technology 11
7.1 Basic technologies for embedding 11
7.2 Basic requirements to embedding technology 11
7.2.1 Cleanliness of components, submodules and process 11
7.2.2 ESD 11
7.2.3 Moisture sensitivity 11
7.2.4 Defects 12
8 Tests and measuring methods 12
8.1 Standard atmospheric conditions 12
8.1.1 Standard atmospheric conditions for testing 12
8.1.2 Referee conditions 12
8.1.3 Reference conditions 13
8.2 Electrical performance tests 13
8.2.1 General 13
8.2.2 Electrical test levels 13
8.2.3 Protection of DES and test equipment 13
8.2.4 Accuracy of measurement 14
8.2.5 Test structures 15
8.2.6 Mechanical performance tests 15
8.2.7 Resistance to soldering heat 15
8.2.8 Solderability 16
8.2.9 Shock 16
8.2.10 Vibration (sinusoidal) 16

AVA Documents
Document Sharing Hub

Full document details: BS EN IEC 62878-1:2019

8.2.11 Resistance to solvents 16
8.3 Climatic performance tests 16
8.3.1 Dry heat 16
8.3.2 Cold 17
8.3.3 Damp heat, steady state 17
8.3.4 Change of temperature 17
9 Transportation, handling and packing material 18
9.1 Humidity / Temperature / Environmental protection 18
9.2 Mechanical protection 18
9.3 ESD 18
10 General requirements 18
Bibliography 19

Figure 1 – Value chain and interfaces 9

Table 1 – Referee conditions 12

Documents
Document Sharing Hub

Full document details: BS EN IEC 62878-1:2019